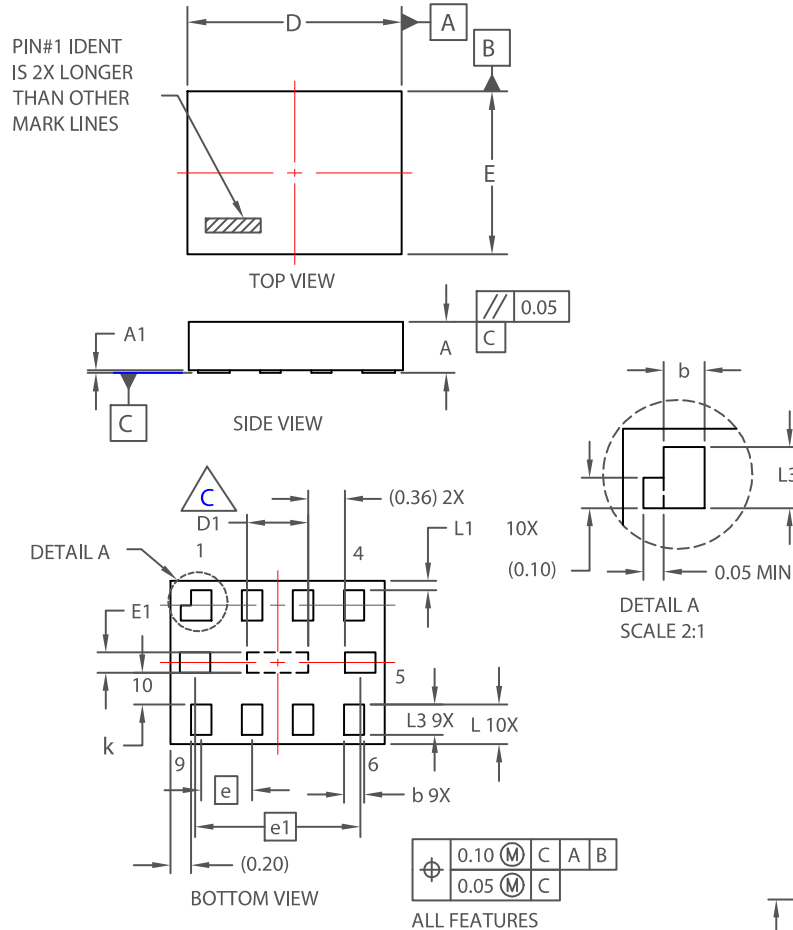




UQFN10 (MICROPAK™), 1.6X2.1, 0.5P
CASE 523AZ
ISSUE A

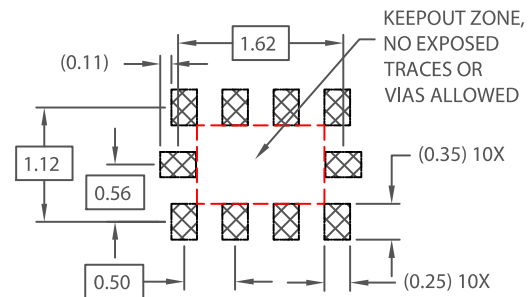
DATE 11 DEC 2019



NOTES:

- A. PACKAGE CONFORMS TO JEDEC REGISTRATION MO-255, VARIATION UABD.
B. DIMENSIONS ARE IN MILLIMETERS.
C. PRESENCE OF CENTER PAD IS PACKAGE SUPPLIER DEPENDENT. IF PRESENT IT IS NOT INTENDED TO BE SOLDERED AND HAS A BLACK OXIDE FINISH.
D. DIMENSIONS WITHIN () ARE UNCONTROLLED.

DIM	MIN.	NOM.	MAX.
A	0.50	0.55	0.65
A1	0.00	0.025	0.05
b	0.15	0.20	0.25
D	2.00	2.10	2.20
D1	0.55	0.60	0.65
E	1.50	1.60	1.70
E1	0.15	0.20	0.25
e	0.50 BSC		
e1	1.62 BSC		
k	0.20	--	--
L	0.25	0.30	0.42
L1	0.00	0.09	0.15
L3	0.25	0.30	0.35



**RECOMMENDED
MOUNTING FOOTPRINT ***

*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERM/D.

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